ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 16721

Generic Copy

Issue Date: 09-Sep-2011

TITLE: VHVIC 2nd Source Qualification to Gresham FAB – Phase 2

PROPOSED FIRST SHIP DATE: 09-Dec-2011

AFFECTED CHANGE CATEGORY(S): Wafer Fab location

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Scott Brow<Scott.Brow@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Ken Fergus<Ken.Fergus@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

The purpose of this final PCN is to notify customers of the qualification of a second source for the devices listed in this FPCN at ON Semiconductor's wafer fabrication facilities in Gresham, Oregon.

This qualification is being made to increase the capacity for these devices. This technology is currently produced out of ON Semiconductor's wafer fabrication facilities in Aizu, Japan.

These devices are being duplicated at the Gresham wafer FAB. No die design changes have occurred. No changes to the device performance, data sheets or packaging have been made.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

NCP1271D65R2G

#	Test	Test Conditions	Read Points	Sample Size	Results
1	HTBB	TA=125C, 450V Bias	Test @ 1008hrs	3 lots x 80 units	0/240
2	HVTHB	TA=85C, 60%RH, 450V Bias	Test @ 168hrs	3 lots x 80 units	0/240
3	HTOL	TA=125C, 100V Bias	Test @ 1008hrs	3 lots x 80 units	0/240
4	HTSL	TA=150C	Test @ 1008hrs	3 lots x 80 units	0/240
5	TC-PC	-65C to +150C	Test @ 500 Cycles	3 lots x 80 units	0/240
6	AC-PC	TA=121C, RH=100%, PSI=15	Test @ 96hrs	3 lots x 80 units	0/240
7	UHAST-PC	TA=130C, RH=85%, PSI=18.8 no Bias	Test @ 1008hrs	3 lots x 80 units	0/240
8	HAST-PC	TA=130C, RH=85%, PSI=18.8 Bias	Test @ 1008hrs	3 lots x 80 units	0/240
9	SAT-PC	Post MSL3 260C	Pre and Post PC	3 lot x 5 units	0/15

NCP1396ADR2G

#	Test	Test Conditions	Read Points	Sample Size	Results
1	HTBB	TA=125C, 600V Bias	Test @ 1008hrs	3 lots x 80 units	0/239*
2	HTOL	TA=125C, 600V Bias	Test @ 1008hrs	3 lots x 80 units	0/240
3	HTSL	TA=150C	Test @ 1008hrs	3 lots x 80 units	0/240
4	TC-PC	-65C to +150C	Test @ 500 Cycles	3 lots x 80 units	0/240
5	AC-PC	TA=121C, RH=100%, PSI=15	Test @ 96hrs	3 lots x 80 units	0/240
6	UHAST-PC	TA=130C, RH=85%, PSI=18.8 no Bias	Test @ 1008hrs	3 lots x 80 units	0/240
7	HAST-PC	TA=130C, RH=85%, PSI=18.8 Bias	Test @ 1008hrs	3 lots x 80 units	0/240
8	SAT-PC	Post MSL3 260C	Pre and Post PC	3 lot x 5 units	0/15

* (1) EOS failure after 504hrs

NCP1237AD65R2G

#	Test	Test Conditions	Read Points	Sample Size	Results
1	HTBB	TA=125C, 500V Bias	Test @ 1008hrs	3 lots x 80 units	0/240
3	HTOL	TA=125C, 380V Bias	Test @ 1008hrs	3 lots x 80 units	0/240
4	HTSL	TA=150C	Test @ 1008hrs	3 lots x 80 units	0/240
5	TC-PC	-65C to +150C	Test @ 500 Cycles	3 lots x 80 units	0/240

SCY991900DWR2G

#	Test	Test Conditions	Read Points	Sample Size	Results
1	HTOL	TA=125C, 600V Bias	Test @ 1008hrs	1 lot x 80 units	0/79*
2	TC-PC	-65C to +150C	Test @ 500 Cycles	1 lot x 80 units	0/80

* (1) EOS failure after 504hrs

NCP1380BDR2G

#	Test	Test Conditions	Read Points	Sample Size	Results
1	HTOL	TA=125C, 30V Bias	Test @ 1008hrs	1 lot x 80 units	0/80
2	TC-PC	-65C to +150C	Test @ 500 Cycles	1 lot x 80 units	0/80

NCP4303ADR2G

#	Test	Test Conditions	Read Points	Sample Size	Results
1	HTOL	TA = 125C, 200V Bias	Test @ 1008hrs	1 lot x 80 units	0/80

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ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

CHANGED PART IDENTIFICATION:

Affected products with date code WW36-2011 and greater may be sourced from either Gresham or Aizu wafer Fabrication site.

List of affected General Parts:

NCP4303ADR2G
NCP4303BDR2G
NCP4303AMNTWG
NCP4303BMNTWG